

ABSTRACT

An object of the present invention is to provide a photosensitive element having superior sensitivity and resolution with respect to exposure by light having a wavelength of 400 to 450 nm in particular and having a rectangular shape for the cross-sectional shape of the resist after developing, a resist pattern formation method, and a printed wiring board production method.

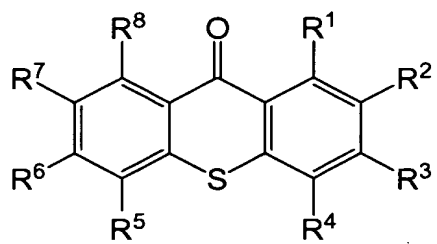
The present invention is a photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition containing (A) a binder polymer, (B) a photopolymerizable compound, and (C) a photopolymerization initiator, wherein,

the photosensitive resin composition contains a thioxanthone-based compound represented by the following general formula (I) as the component (C), and

when the parts by weight of the thioxanthone-based compound relative to 100 parts by weight for the total weight of the component (A) and the component (B) is taken to be P, and the film thickness of the photosensitive resin composition layer is taken to be Q (μm), then R, which is the product of P and Q, satisfies the condition of the following formula (1). In the following general formula (I), R^1 to R^8 represent a hydrogen atom, halogen atom or hydrocarbon group.

$$25.5 \leq R \leq 79.0 \quad (1)$$

[Chemical Formula 1]



(I)